

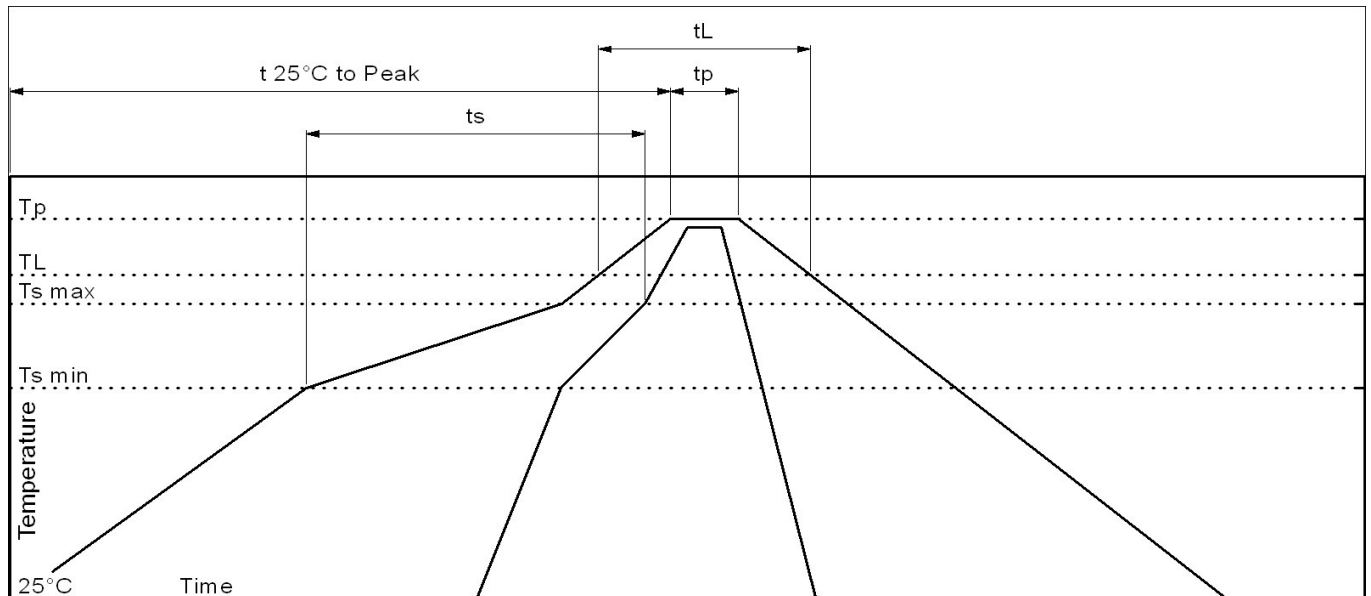
RoHS SMD PRODUCTS SOLDERING GUIDELINES

1. WASHING CONDITIONS

Our non hermetic SMD products are strictly non-washable as liquid cleaning solutions could penetrate the base to cap seal.
No-washing type flux with no washing is highly recommended. Please consult factory for any other process.

2. REFLOW SOLDERING CONDITIONS

Reflow profile:



PROFILE DATA

Minimum preheat temperature	Ts min	150°C
Maximum preheat temperature	Ts max	200°C
Preheat time	Ts min to TS max	60 - 180 seconds
Average ramp-up rate	Ts max to Tp	3°C/second max.
Reflow temperature	TL	217°C
Reflow time	tL	60 - 150 seconds
Peak temperature	Tp	250°C for S2 package 245°C for other package
Peak time	tp	20 - 40 seconds
Average down ramp rate		6°C/seconds max.
Time 25°C to peak temperature		8 minutes max.

This profile is applicable for the following packages: S1, S2, S4, S5, S7, S8, S11, S13, and S15

Additional recommendations:

- Do not vibrate during reflow soldering
- Do not reflow solder on back side
- Only one reflow is allowed
- Solder adhesion may vary depending on the motherboard's thermal capacity and other factors

Hand soldering (not recommended):

Maximum temperature: 300°C/5 sec, fine tipped soldering iron